



Sun Fire™ E6900/E4900/6800/4810/ 4800 Systems PCI I/O Assembly Installation Guide

All systems: If PCI I/O assemblies are to be mixed with CompactPCI I/O assemblies, install the CompactPCI I/O assemblies only in IB8 or IB9 for cooling purposes.

Sun Fire™ E6900/6800 systems only: When you install PCI I/O assemblies, you can install them in either the top or bottom I/O locations. Populate the I/O assemblies from right to left.

Location of I/O Assemblies

System	Slot Numbers	Slot Location
Sun Fire E6900/6800 System	IB6, IB7, IB8, and IB9	Rear—bottom right and left, top right and left
Sun Fire E4900/4800 System	IB6, IB8	Rear—bottom and top

Installing a PCI I/O Assembly

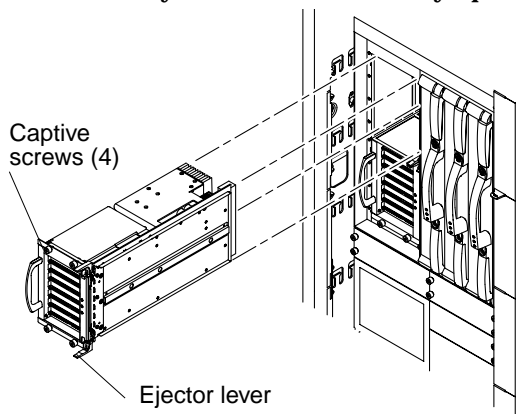
Note – The PCI I/O assembly can be inserted into a powered-on system. However, the assembly will not be recognized by the system until the domain has been dynamically reconfigured to include the assembly, or re-initialized and rebooted. Refer to the system administration manual for your product for complete procedures for initializing a domain. Refer to the dynamic reconfiguration manual for your product for complete DR procedures.

1. Place a grounded ESD mat close to the system.
2. Wear an ESD strap and connect it to the system.



Caution – You must install the I/O assembly within one minute of removing the filler panel to prevent overheating.

3. Remove the filler panel from the front of the I/O assembly location and store it for possible future use.
4. Line up the I/O assembly with the I/O assembly opening.



5. Insert the assembly into the card cage opening.

The ejector levers should be toward the inside of the I/O assembly and in the open position



Caution – DO NOT FORCE any assembly into a slot; this can cause damage to the assembly and system. The assembly should insert and seat smoothly. If it binds, remove the assembly and inspect the card cage slot for any obvious obstructions.

6. Simultaneously press the two ejector levers inward.
7. Tighten the four captive screws.

Note – The assembly will not be recognized by the system until the domain has been reconfigured to include the board, or re-initialized and rebooted.

8. Reconfigure the I/O assembly back into the system by either of the following procedures:
 - Dynamically reconfigure the I/O assembly back into the domain. Refer to the dynamic reconfiguration manual for your product.
 - Power on the I/O assembly and initialize the domain. Refer to the system administration manual for your product.

Note – After reconfiguration, the Activated LED should be on (lit).

Removing a PCI I/O Assembly



Caution – Remove an assembly from a powered-on system only after the Solaris Operating Environment dynamic reconfiguration (DR) software has disabled that assembly. Refer to the dynamic reconfiguration manual for your product.



Caution – You must install a filler panel, which covers only the front of the assembly slot, within one minute of removing the I/O assembly to prevent overheating.

1. Prepare the system for removal of the PCI I/O assembly.

Two methods can be used to prepare the assembly:

- Refer to the system administration manual for your product for complete procedures for powering off the assembly.
- If the assembly is being used by the Solaris Operating Environment, identify the assembly to be removed, then dynamically reconfigure the assembly out of the domain. Refer to the dynamic reconfiguration manual for your product for complete procedures before removing the I/O assembly.

Note – In order to safely remove the I/O assembly from the system, the green Activated LED on the board must be off (not lit) and the amber OK to remove LED must be on (lit).

2. Wait until the LEDs indicate that the assembly is out of the domain.

3. Place a grounded ESD mat close to the system.

4. Wear an ESD strap and connect it to the system.

5. Loosen the four captive screws.

6. Simultaneously pull the two ejector levers outward to unseat the I/O assembly.

This action releases the board from the connectors.

7. Remove the assembly from the card cage.

8. Place the assembly on the ESD mat.

9. Install a filler panel.

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